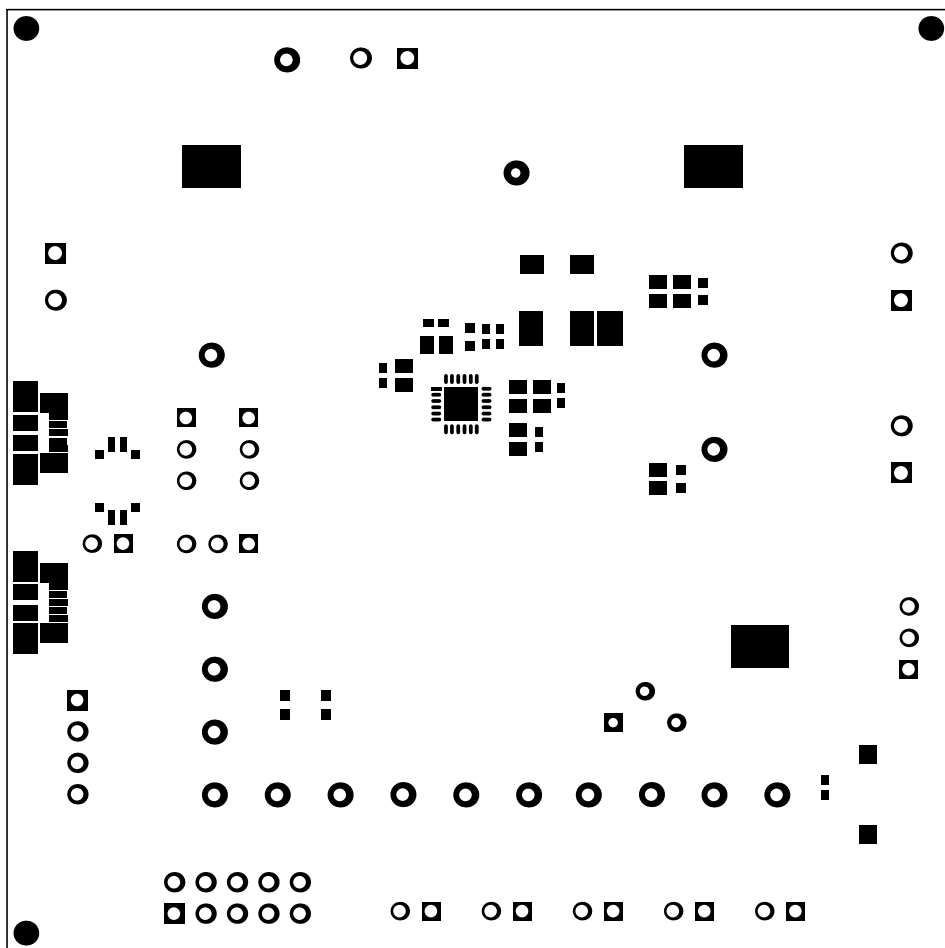


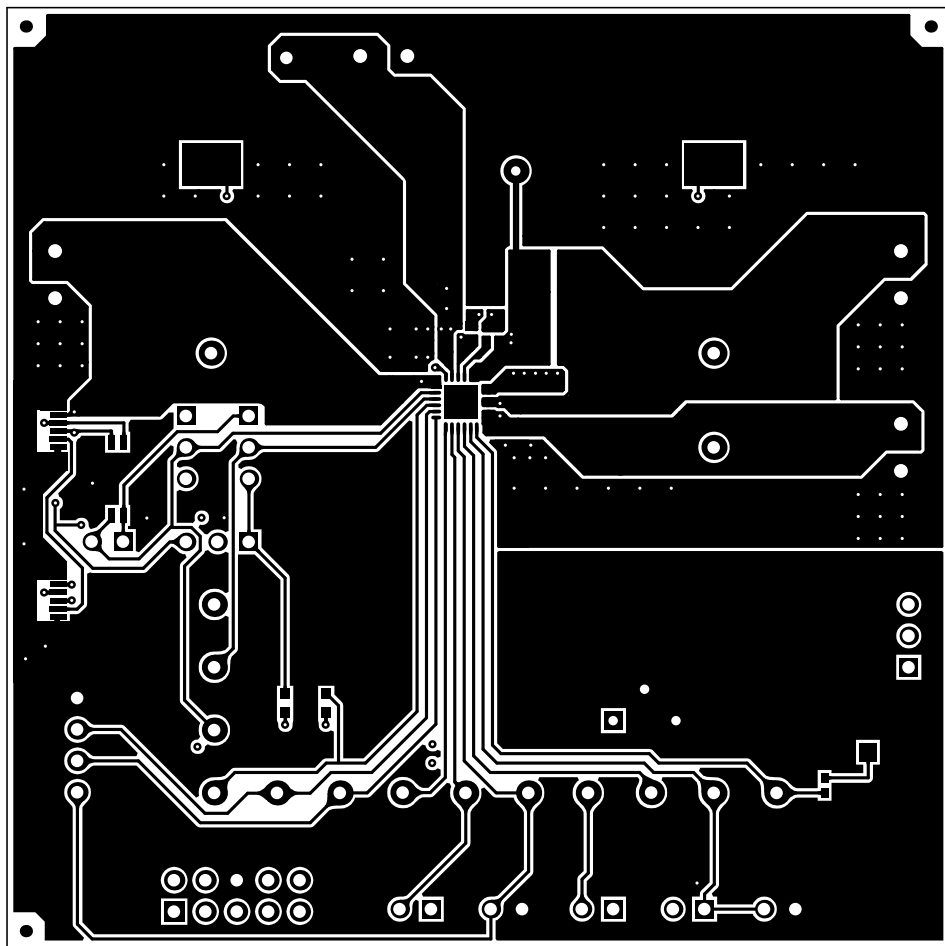
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Top Overlay			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



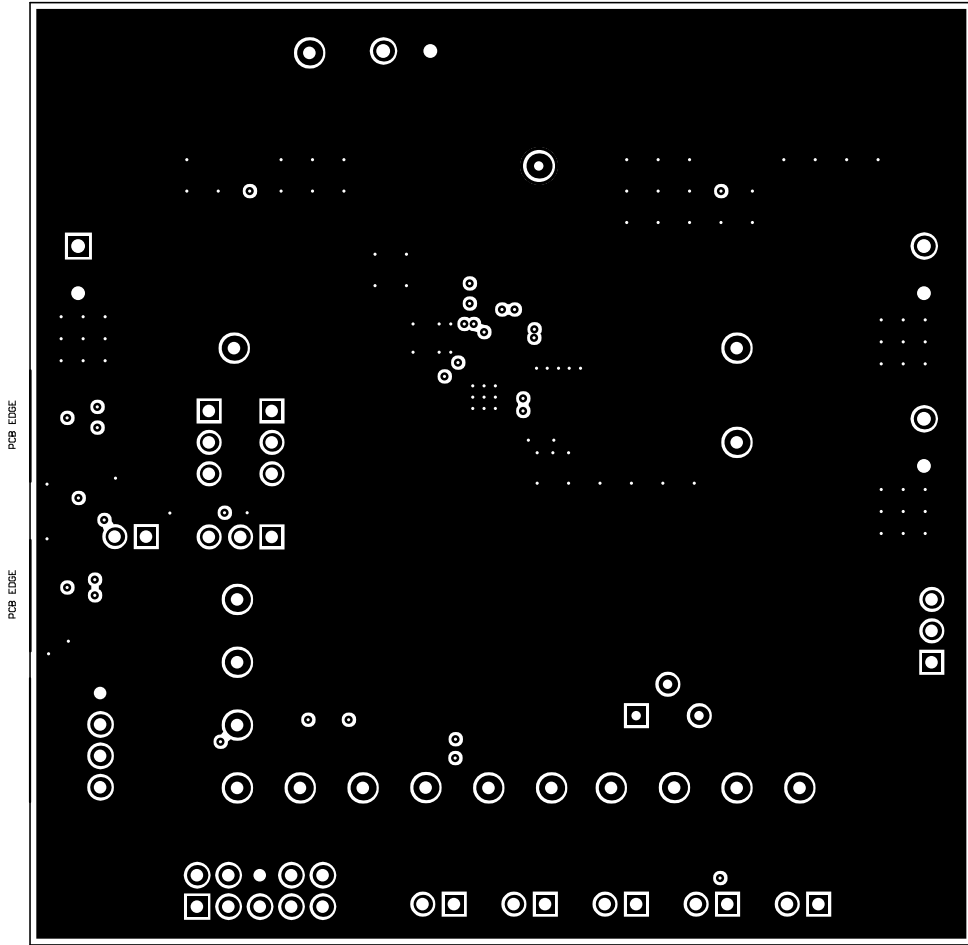
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Top Solder			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



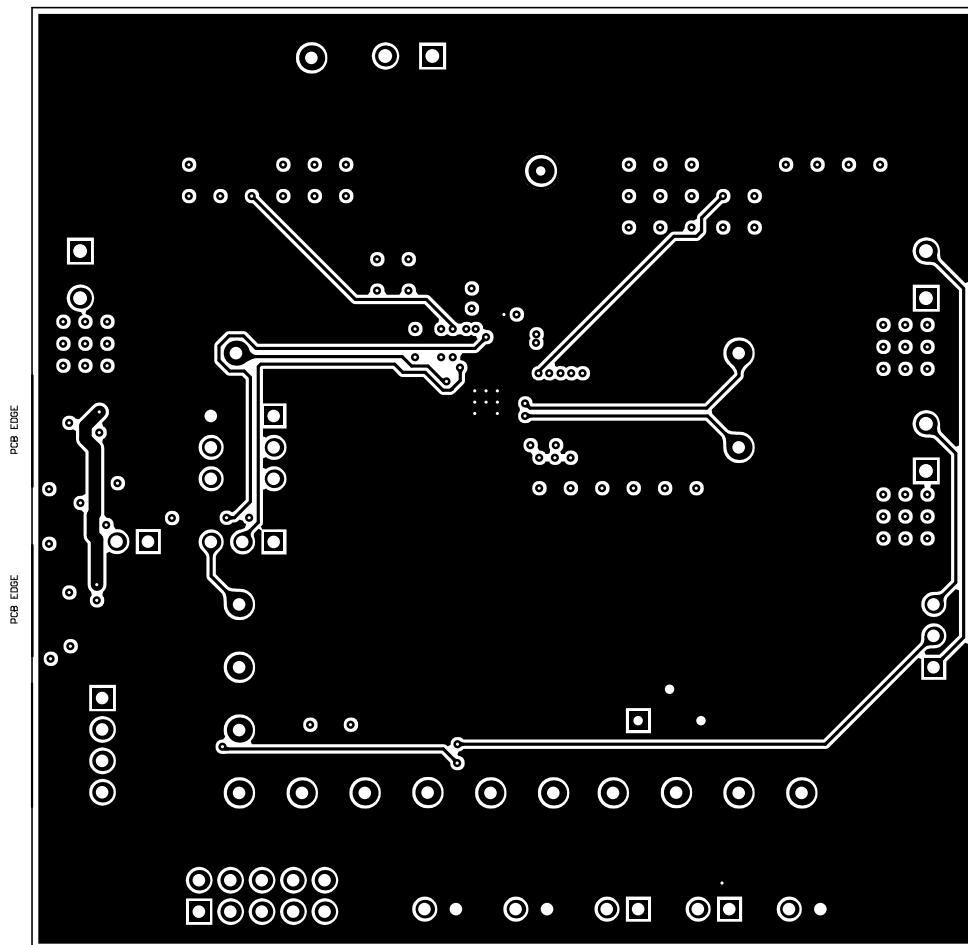
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Top Layer			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



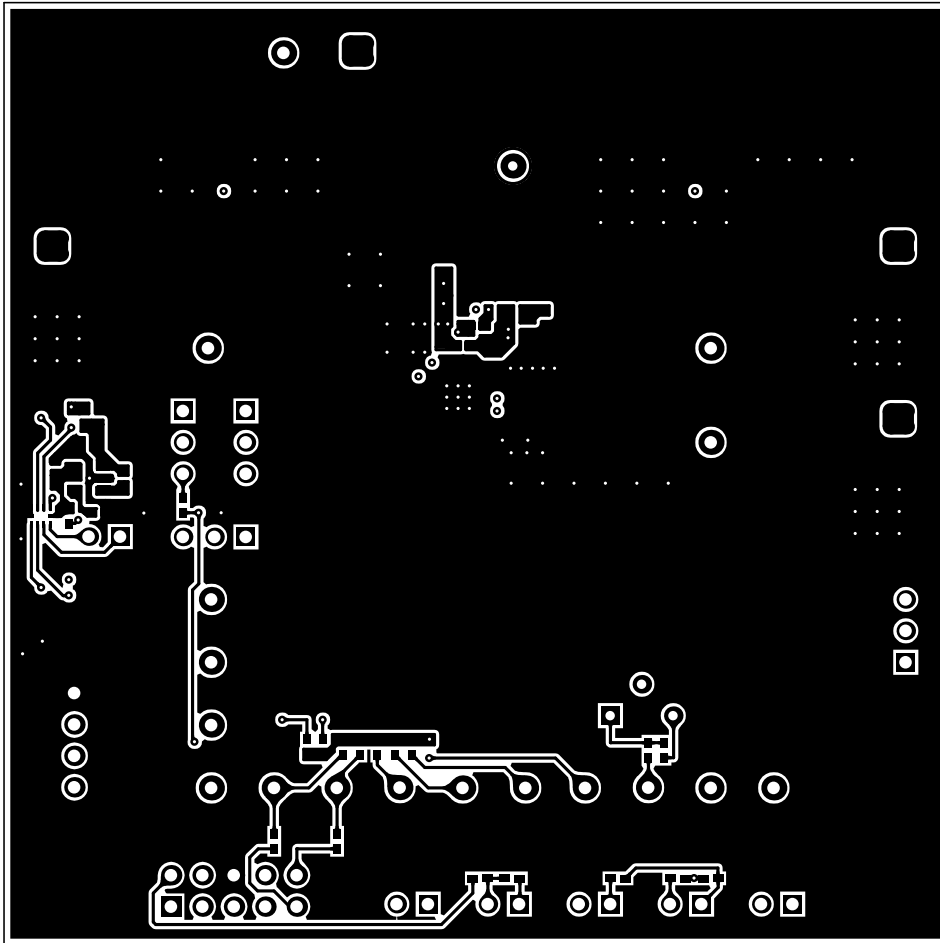
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = MidBaged10Outline			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



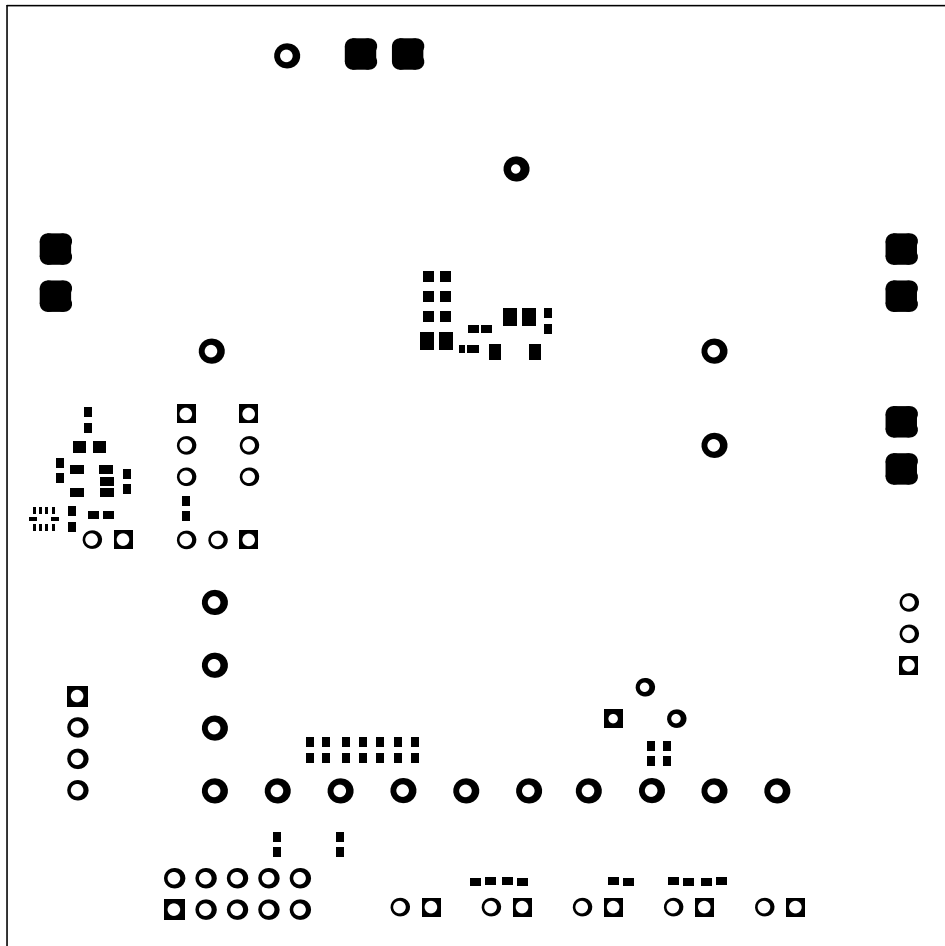
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = MidBaged20outline			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



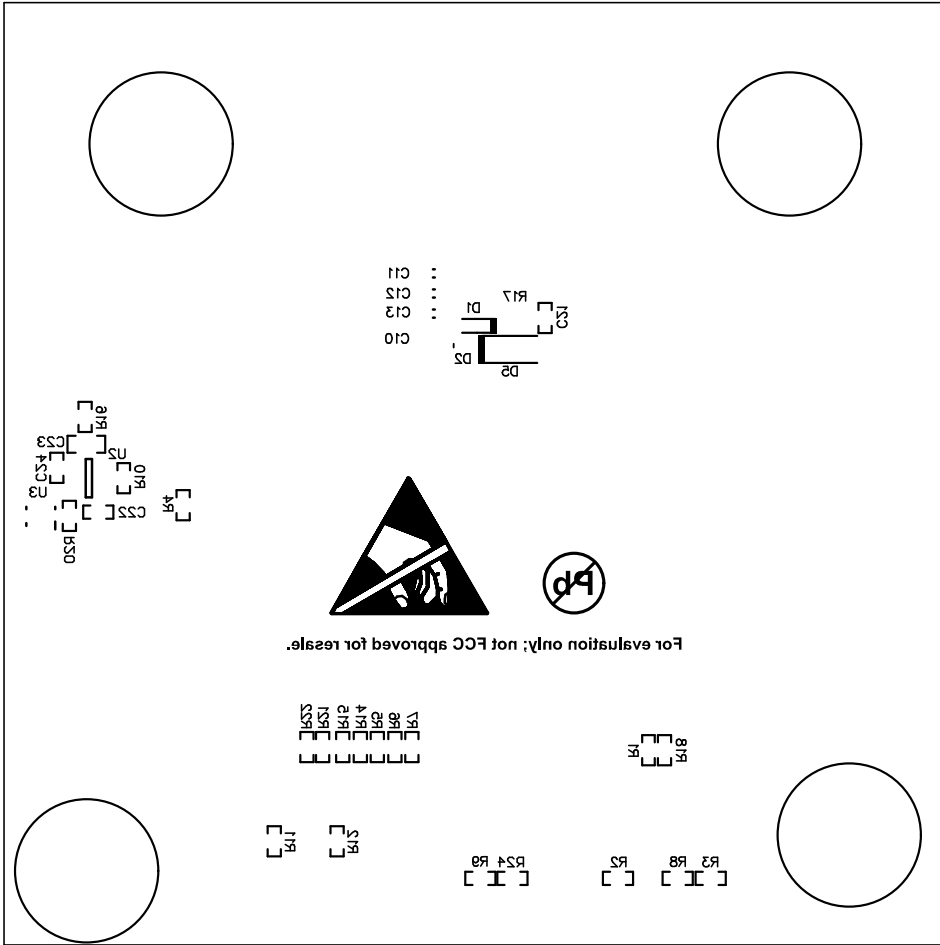
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Bottom Layer			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



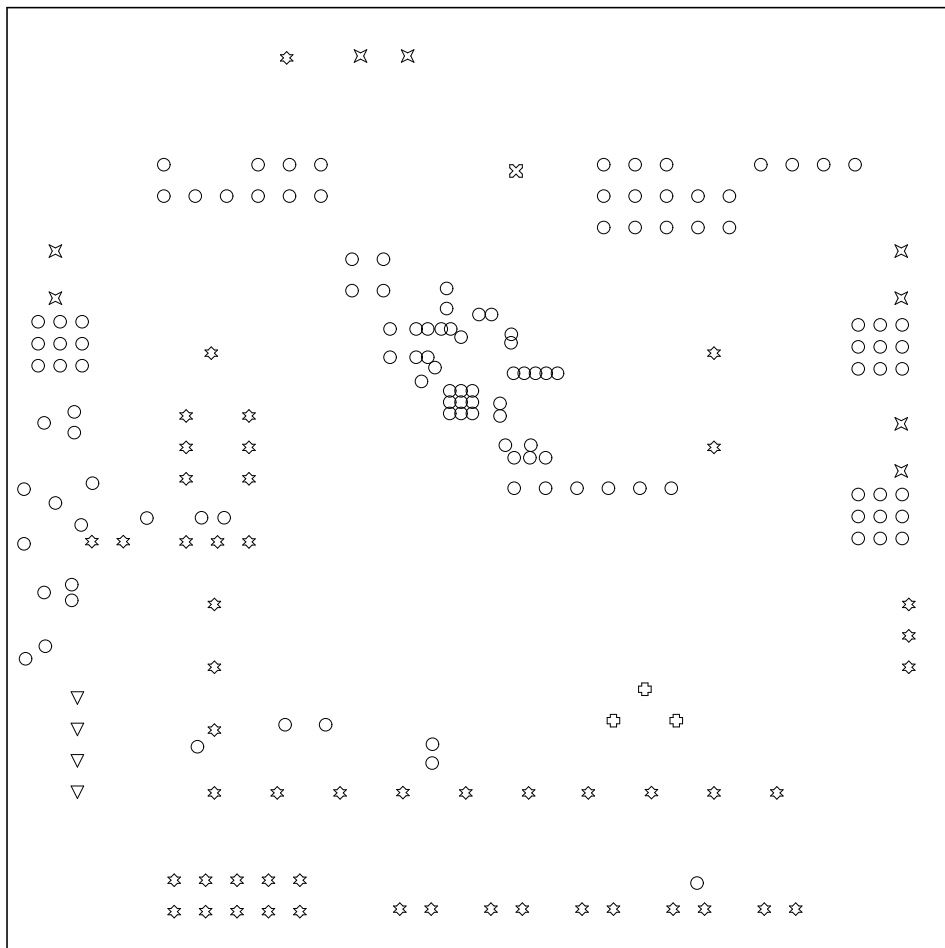
TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Bottom Solder			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



TIDA-00538
PWR664A

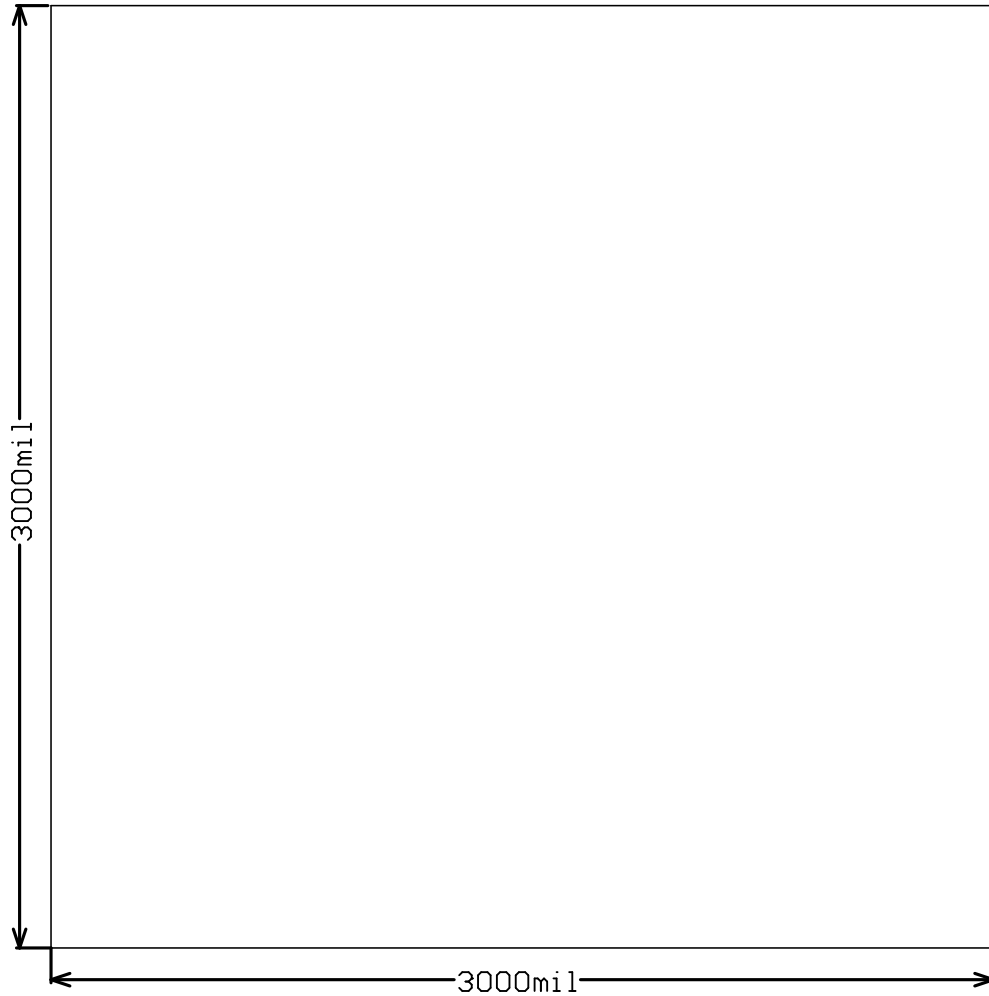
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Bottom Overlay			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



Legend is not interpreted until output
Drill Table

TIDA-00538
PWR664A

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = Drill Drawing			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	



TIDA-00538
PWR664A



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR664	REV: A	SUN REV:
LAYER NAME = M2 Board Dimensions			
PLOT NAME =	GENERATED : 02/23/2015	TEXAS INSTRUMENTS	

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